

CLIPPEDIMAGE= JP410270817A

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TITLE: CIRCUIT BOARD, SUSPENSION BOARD WITH CIRCUIT, AND
THEIR MANUFACTURE

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ABSTRACT:

PROBLEM TO BE SOLVED: To provide a circuit board which has
an insulating layer
made of a polyimide resin having a low hygroscopic property
and formed on a
metallic foil substrate and such high dimensional stability
that the board does
not warp even when the moisture in the environmental
atmosphere changes and a
suspension board with circuit using the circuit board.

SOLUTION: In a circuit board having an insulating layer 3
made of a polyimide
resin and formed on a metallic foil substrate 2, the
insulating layer 3 is
formed by using a polyimide resin which is obtained through
the reaction

between an aromatic diamine composed of
1,3-bis(4-aminophenoxy) benzene and
2,2'-bis(trifluoromethyl)-4,4'-diaminobiphenyl and an
aromatic tetracarboxylic
acid dianhydride composed of 3,4,3',4'-biphenyl
tetracarboxylic acid
dianhydride and 2,2-bis(3,4-dicarboxyphenyl)
hexafluoropropane dianhydride. A
suspension board 1 with circuit is formed by patterning a
desired circuit
composed of a conductor layer on such a circuit board.

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